

# 74AHC125; 74AHCT125

Quad buffer/line driver; 3-state

Rev. 8 — 28 April 2025

Product data sheet

## 1. General description

The 74AHC125; 74AHCT125 is a quad buffer/line driver with 3-state outputs controlled by the output enable inputs ( $\overline{nOE}$ ). A HIGH on  $\overline{nOE}$  causes the outputs to assume a high impedance OFF-state. Inputs are overvoltage tolerant. This feature allows the use of these devices as translators in mixed voltage environments.

## 2. Features and benefits

- Wide supply voltage range from 2.0 V to 5.5 V
- Overvoltage tolerant inputs to 5.5 V
- High noise immunity
- CMOS low power dissipation
- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Input levels:
  - For 74AHC125: CMOS level
  - For 74AHCT125: TTL level
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level A
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
<a href="#">74AHC125D</a> <a href="#">74AHCT125D</a>	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	<a href="#">SOT108-1</a>
<a href="#">74AHC125PW</a> <a href="#">74AHCT125PW</a>	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	<a href="#">SOT402-1</a>
<a href="#">74AHC125BQ</a> <a href="#">74AHCT125BQ</a>	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	<a href="#">SOT762-1</a>
<a href="#">74AHC125BZ</a> <a href="#">74AHCT125BZ</a>	-40 °C to +125 °C	DHXQFN14	plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package; no leads; 14 terminals; 0.4 mm pitch; body 2 mm × 2 mm × 0.48 mm	<a href="#">SOT8014-1</a>

4. Functional diagram

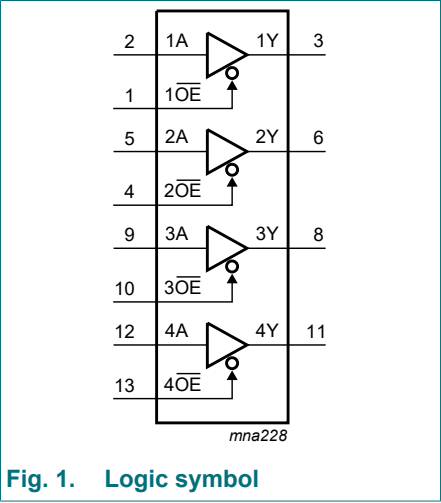


Fig. 1. Logic symbol

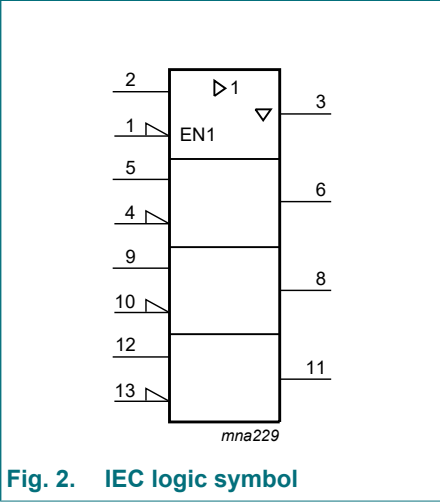


Fig. 2. IEC logic symbol

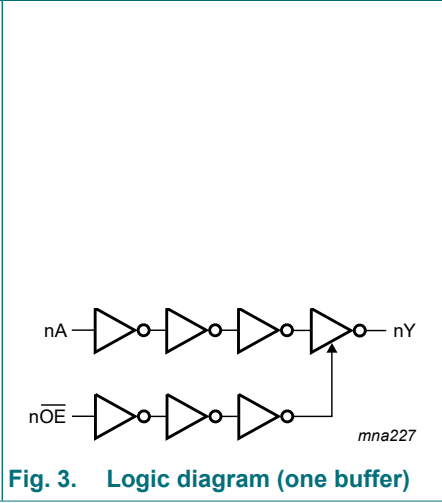


Fig. 3. Logic diagram (one buffer)

5. Pinning information

5.1. Pinning

**D package**  
**SOT108-1 (SO14)**

aaa-036122

**PW package**  
**SOT402-1 (TSSOP14)**

aaa-036123

**BQ package**  
**SOT762-1 (DHVQFN14)**

aaa-036121

Transparent top view

**BZ package**  
**SOT8014-1 (DHXQFN14)**

aaa-041313

Transparent top view

(1) This is not a ground pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to GND.

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1OE, 2OE, 3OE, 4OE	1, 4, 10, 13	output enable input (active LOW)
1A, 2A, 3A, 4A	2, 5, 9, 12	data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
VCC	14	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Control	Input	Output
nOE	nA	nY
L	L	L
	H	H
H	X	Z

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
V <sub>I</sub>	input voltage		-0.5	+7.0	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V [1]	-20	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V [1]	-	±20	mA
I <sub>O</sub>	output current	V <sub>O</sub> = -0.5 V to (V <sub>CC</sub> + 0.5 V)	-	±25	mA
I <sub>CC</sub>	supply current		-	75	mA
I <sub>GND</sub>	ground current		-75	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	SOT108-1, SOT402-1, SOT762-1 T <sub>amb</sub> = -40 °C to +125 °C [2]	-	500	mW
		SOT8014-1 T <sub>amb</sub> = -40 °C to +125 °C [3]	-	250	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- [2] For SOT108-1 (SO14) package: P<sub>tot</sub> derates linearly with 10.1 mW/K above 100 °C.  
For SOT402-1 (TSSOP14) package: P<sub>tot</sub> derates linearly with 7.3 mW/K above 81 °C.  
For SOT762-1 (DHVQFN14) package: P<sub>tot</sub> derates linearly with 9.6 mW/K above 98 °C.
- [3] For SOT8014-1 (DHXQFN14) package: P<sub>tot</sub> derates linearly with 8.7 mW/K above 121 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AHC125			74AHCT125			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	5.5	0	-	5.5	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	-	-	100	-	-	-	ns/V
		V <sub>CC</sub> = 5.0 V ± 0.5 V	-	-	20	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74AHC125										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V <sub>CC</sub> = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V <sub>CC</sub> = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I <sub>O</sub> = -8.0 mA; V <sub>CC</sub> = 4.5 V	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I <sub>O</sub> = 8.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.25	-	±2.5	-	±10.0	μA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	2.0	-	20	-	40	μA

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C <sub>I</sub>	input capacitance		-	3.0	10	-	10	-	10	pF
C <sub>O</sub>	output capacitance		-	4.0	-	-	-	-	-	pF
74AHCT125										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -50 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -8.0 mA	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 50 µA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.25	-	±2.5	-	±10.0	µA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	2.0	-	20	-	40	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; I <sub>O</sub> = 0 A; other pins at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C <sub>I</sub>	input capacitance		-	3.0	10	-	10	-	10	pF
C <sub>O</sub>	output capacitance		-	4.0	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

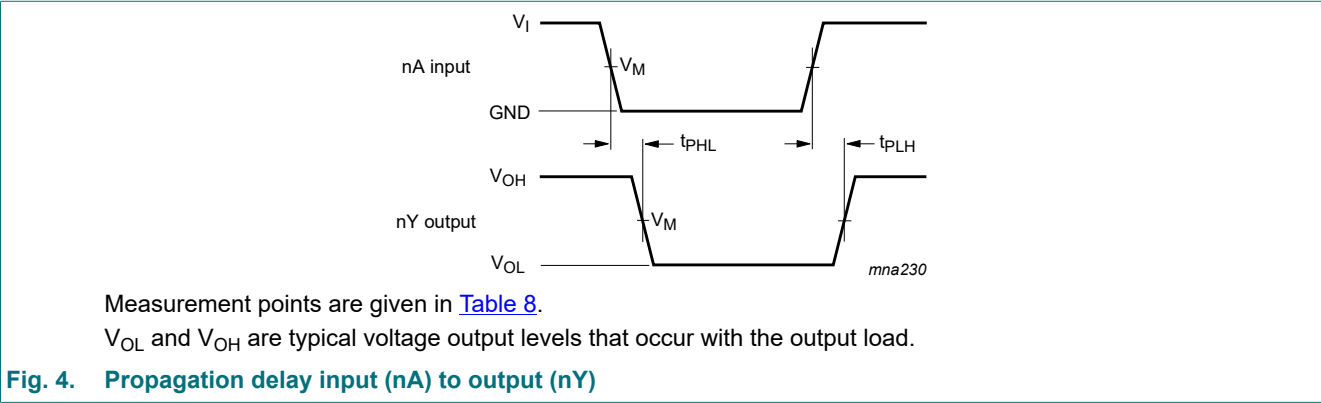
GND = 0 V; For test circuit see Fig. 6.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
74AHC125										
t <sub>pd</sub>	propagation delay	nA to nY; see Fig. 4 [2]								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	4.4	8.0	1.0	9.5	1.0	11.5	ns
		C <sub>L</sub> = 50 pF	-	6.2	11.5	1.0	13.0	1.0	14.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.0	5.5	1.0	6.5	1.0	7.0	ns
		C <sub>L</sub> = 50 pF	-	4.3	7.5	1.0	8.5	1.0	9.5	ns
t <sub>en</sub>	enable time	nOE to nY; see Fig. 5 [2]								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	4.7	8.0	1.0	9.5	1.0	11.5	ns
		C <sub>L</sub> = 50 pF	-	6.8	11.5	1.0	13.0	1.0	14.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.3	5.1	1.0	6.0	1.0	6.5	ns
		C <sub>L</sub> = 50 pF	-	4.7	7.1	1.0	8.0	1.0	9.0	ns
t <sub>dis</sub>	disable time	nOE to nY; see Fig. 5 [2]								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	6.7	9.7	1.0	11.5	1.0	12.5	ns
		C <sub>L</sub> = 50 pF	-	9.6	13.2	1.0	15.0	1.0	16.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.8	6.8	1.0	8.0	1.0	8.5	ns
		C <sub>L</sub> = 50 pF	-	6.8	8.8	1.0	10.0	1.0	11.0	ns
C <sub>PD</sub>	power dissipation capacitance	C <sub>L</sub> = 50 pF; f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> [3]	-	10	-	-	-	-	pF	

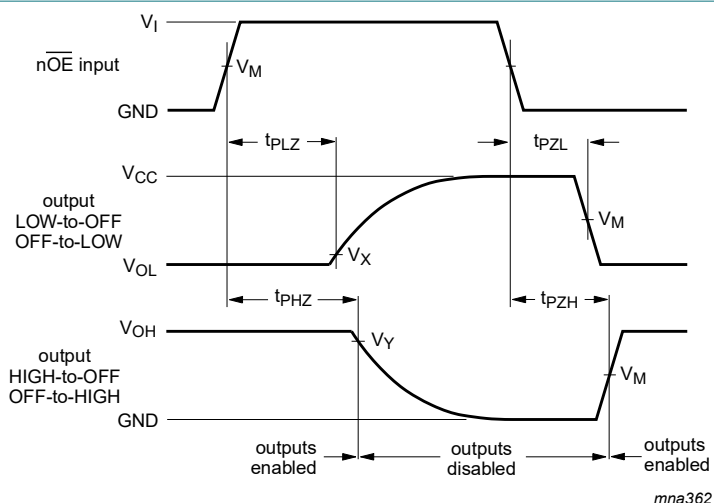
Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
74AHCT125										
t <sub>pd</sub>	propagation delay	nA to nY; see Fig. 4 [2]								
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.0	5.5	1.0	6.5	1.0	7.0	ns
		C <sub>L</sub> = 50 pF	-	4.3	7.5	1.0	8.5	1.0	9.5	ns
t <sub>en</sub>	enable time	n $\overline{\text{OE}}$ to nY; see Fig. 5 [2]								
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.4	5.1	1.0	6.0	1.0	6.5	ns
		C <sub>L</sub> = 50 pF	-	4.9	7.3	1.0	8.3	1.0	9.5	ns
t <sub>dis</sub>	disable time	n $\overline{\text{OE}}$ to nY; see Fig. 5 [2]								
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.5	6.8	1.0	8.0	1.0	8.5	ns
		C <sub>L</sub> = 50 pF	-	6.5	8.8	1.0	10.0	1.0	11.0	ns
C <sub>PD</sub>	power dissipation capacitance	C <sub>L</sub> = 50 pF; f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> [3]	-	12	-	-	-	-	-	pF

- [1] Typical values are measured at nominal supply voltage (V<sub>CC</sub> = 3.3 V and V<sub>CC</sub> = 5.0 V).
- [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.  
t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.
- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
f<sub>i</sub> = input frequency in MHz, f<sub>o</sub> = output frequency in MHz  
C<sub>L</sub> = output load capacitance in pF  
V<sub>CC</sub> = supply voltage in Volts  
N = number of inputs switching  
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

10.1. Waveforms and test circuit







Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig. 5. Enable and disable times**

### Table 8. Measurement points

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74AHC125	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3\text{ V}$	$V_{OL} - 0.3\text{ V}$
74AHCT125	$1.5\text{ V}$	$0.5V_{CC}$	$V_{OL} + 0.3\text{ V}$	$V_{OL} - 0.3\text{ V}$

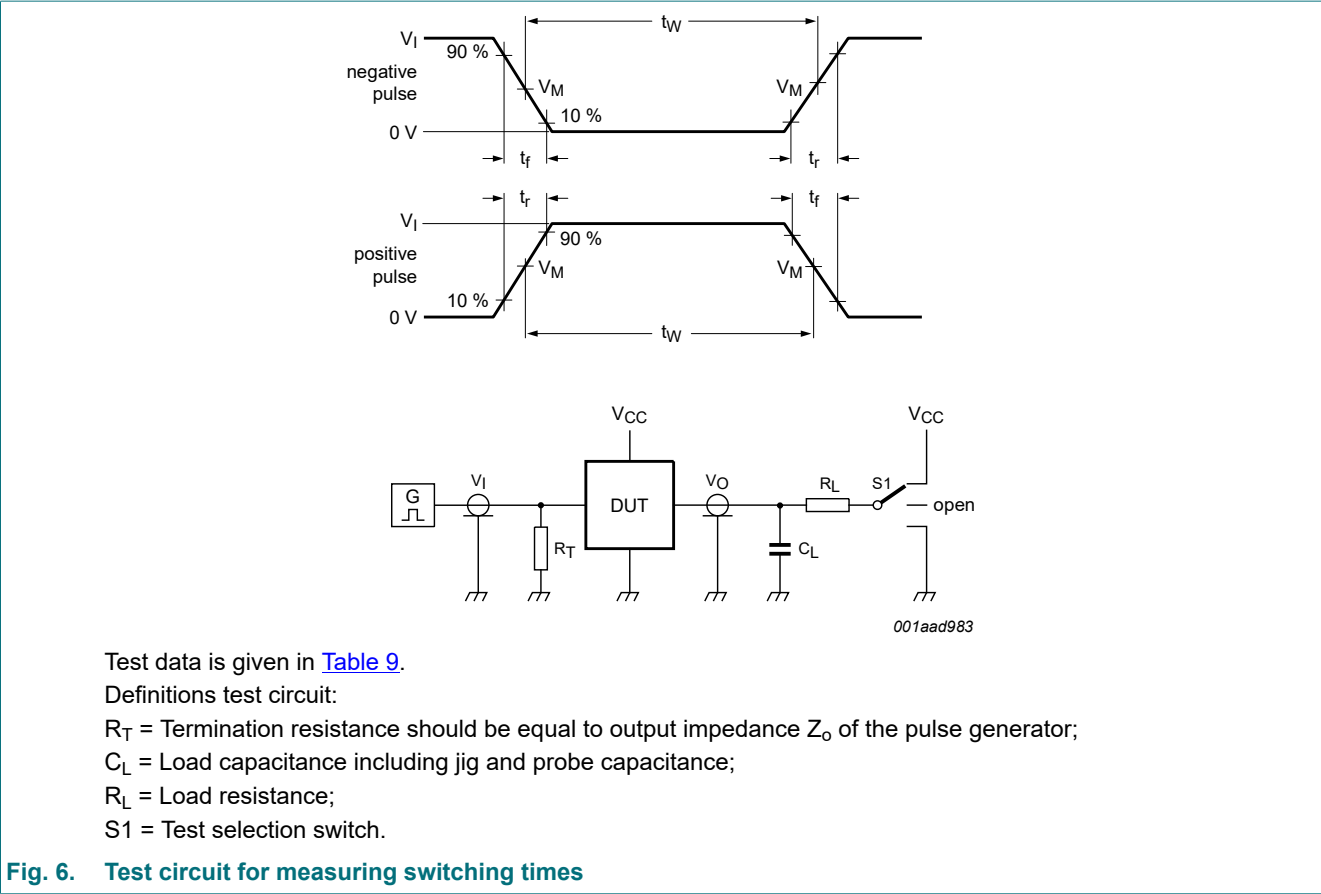


Table 9. Test data

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74AHC125	$V_{CC}$	$\leq 3.0 \text{ ns}$	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74AHCT125	3.0 V	$\leq 3.0 \text{ ns}$	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

11. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mmSOT108-1

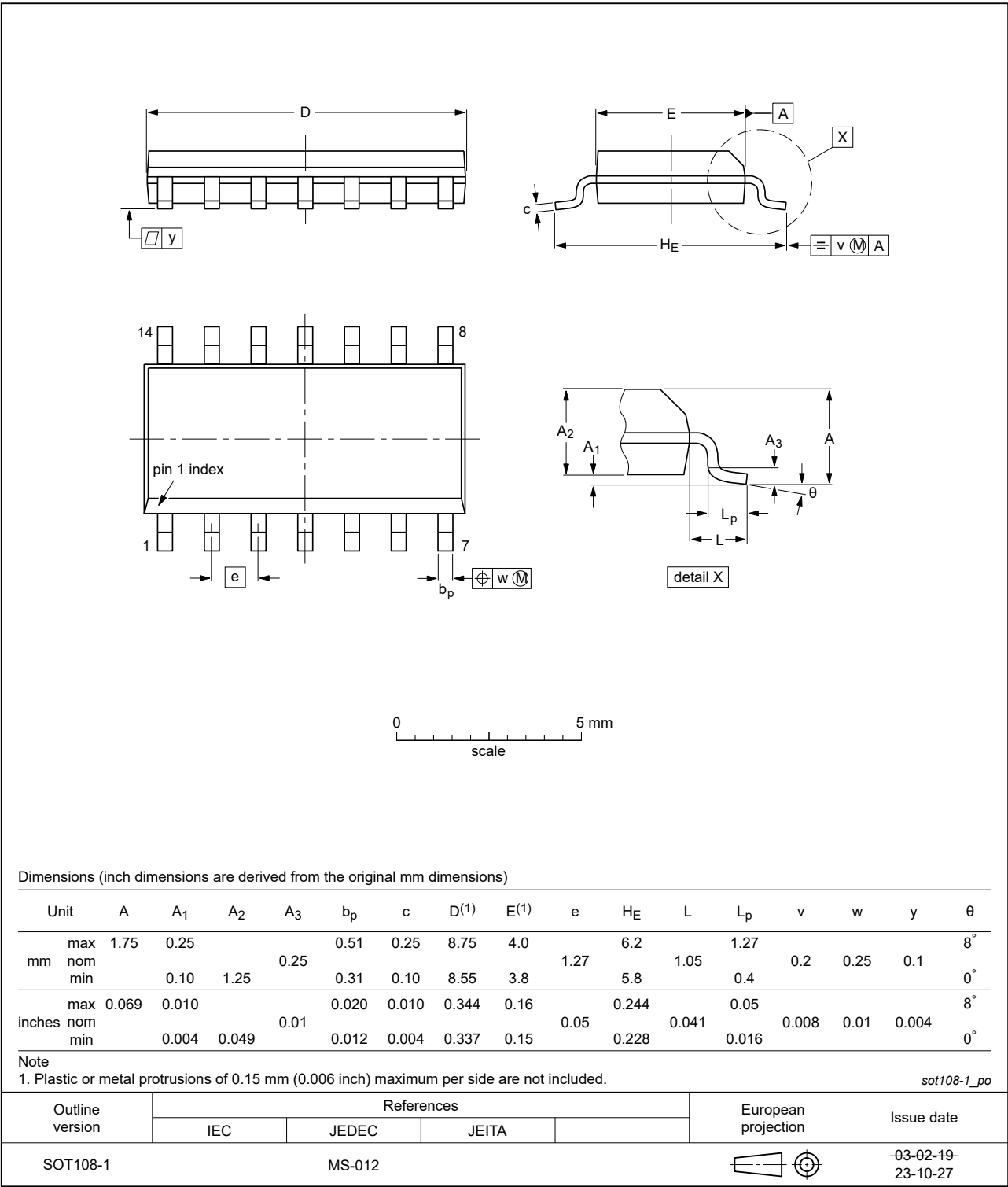


Fig. 7. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

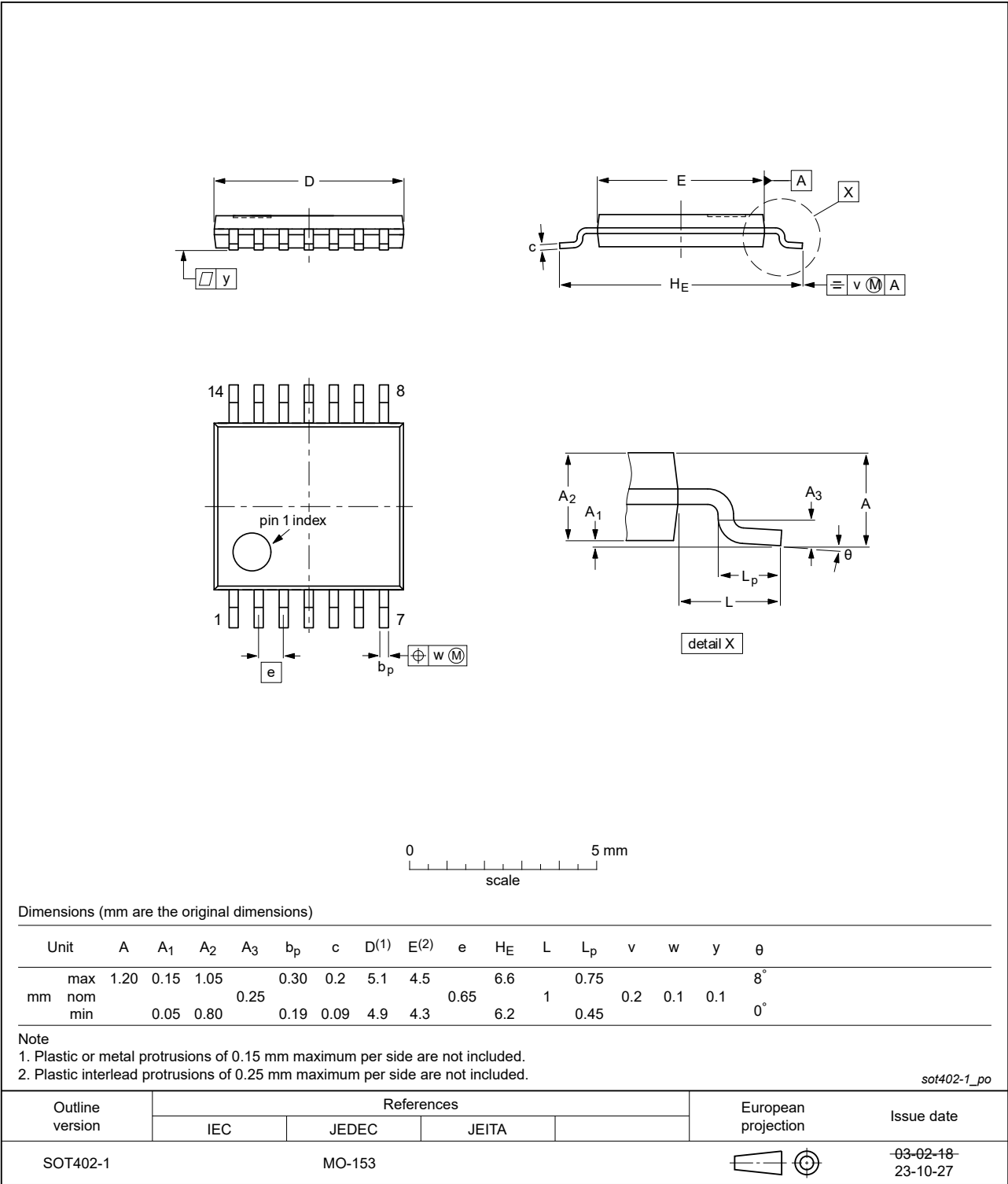


Fig. 8. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;  
14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

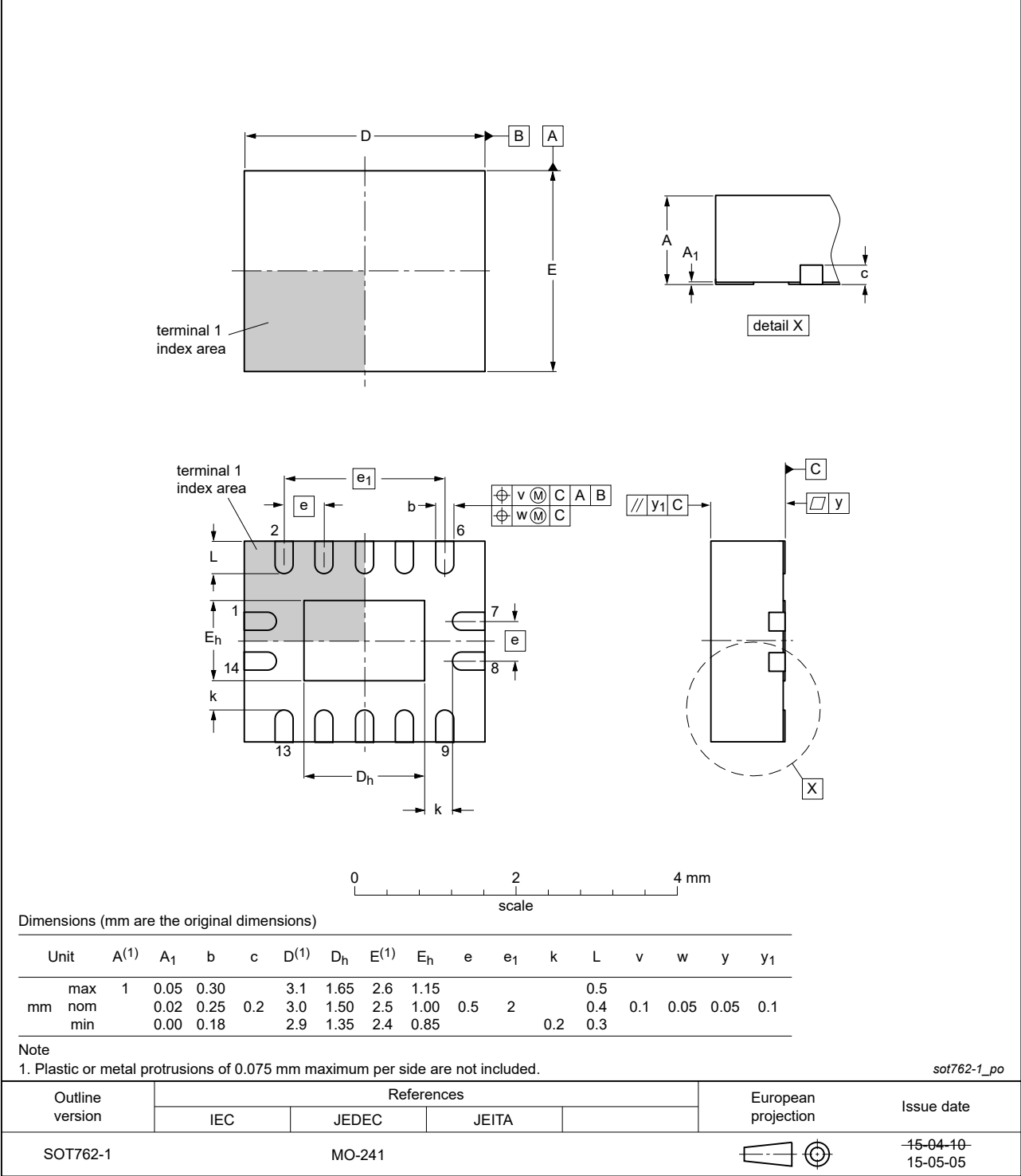


Fig. 9. Package outline SOT762-1 (DHVQFN14)

**DHXQFN14:** plastic, leadless dual in-line compatible thermal enhanced extreme thin quad flat package;  
no leads; 14 terminals; 0.4 mm pitch; body 2 mm x 2 mm x 0.48 mm

SOT8014-1

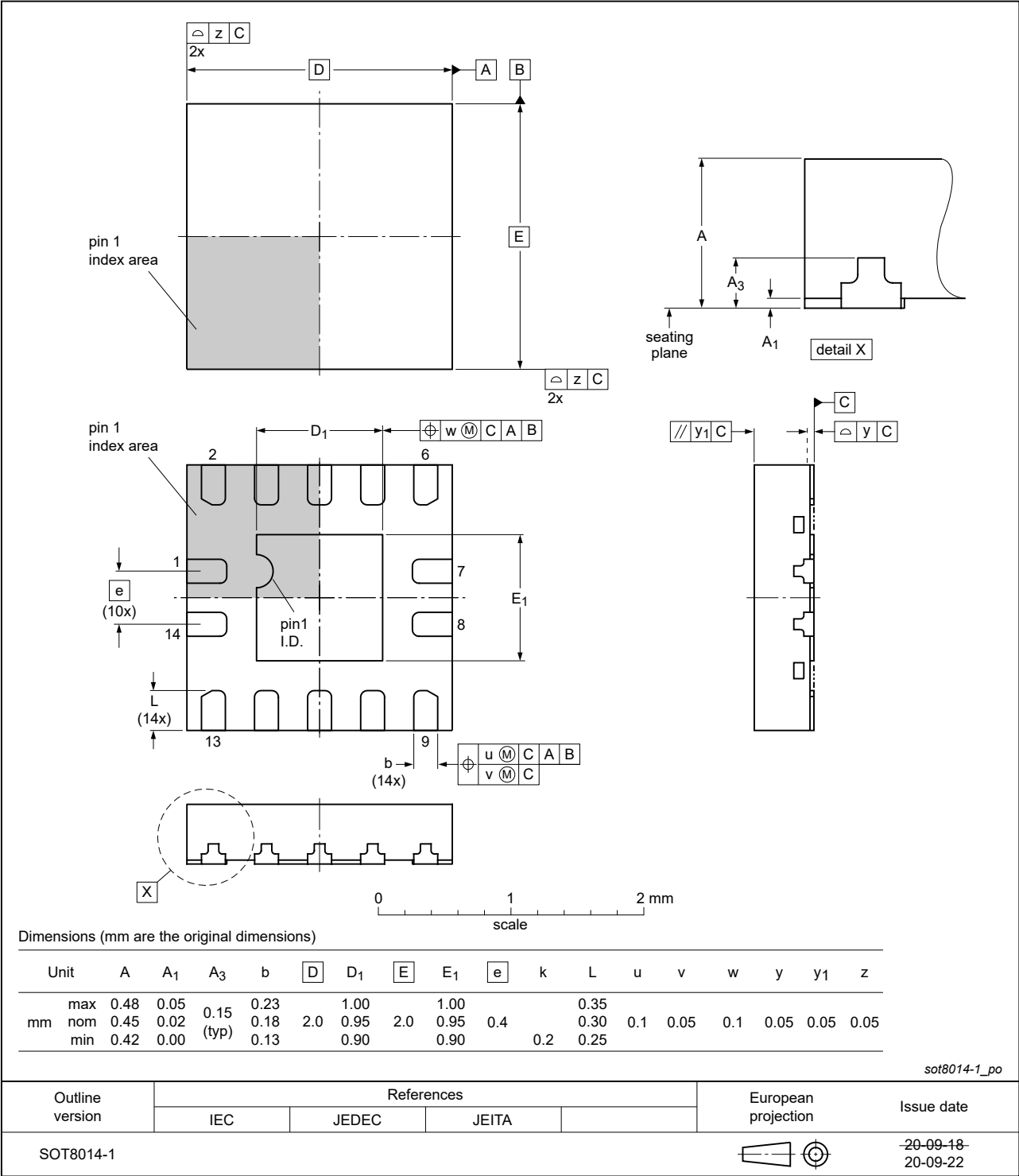


Fig. 10. Package outline SOT8014-1 (DHXQFN14)

12. Abbreviations

Table 10. Abbreviations

Acronym	Description
ANSI	American National Standards Institute
CDM	Charge-Device Model
CMOS	Complementary Metal Oxide Semiconductor
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
HBM	Human Body Model
JEDEC	Joint Electron Device Engineering Council
TTL	Transistor-Transistor Logic

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT125 v.8	20250428	Product data sheet	-	74AHC_AHCT125 v.7
Modifications:	• Type numbers 74AHC125BZ and 74AHCT125BZ125 (SOT8014-1/DHXQFN14) added.			
74AHC_AHCT125 v.7	20240228	Product data sheet	-	74AHC_AHCT125 v.6
Modifications:	• <a href="#">Fig. 7</a> , <a href="#">Fig. 8</a> : Aligned SO and TSSOP package outline drawings to JEDEC MS-012 and MO-153.			
74AHC_AHCT125 v.6	20230904	Product data sheet	-	74AHC_AHCT125 v.5
Modifications:	• <a href="#">Section 2</a> : ESD specification updated according to the latest JEDEC standard.			
74AHC_AHCT125 v.5	20200612	Product data sheet	-	74AHC_AHCT125 v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate. • <a href="#">Section 1</a> and <a href="#">Section 2</a> updated. • <a href="#">Table 4</a> : Derating values for P <sub>tot</sub> total power dissipation have been updated. • <a href="#">Table 6</a> : Conditions for I <sub>OZ</sub> corrected. • Package outline drawing of SOT762-1 ( <a href="#">Fig. 9</a> ) updated.			
74AHC_AHCT125 v.4	20080111	Product data sheet	-	74AHC_AHCT125 v.3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • <a href="#">Section 3</a> : DHVQFN14 package added. • <a href="#">Section 7</a> : derating values added for DHVQFN14 package. • <a href="#">Section 11</a> : outline drawing added for DHVQFN14 package.			
74AHC_AHCT125 v.3	20060324	Product data sheet	-	74AHC_AHCT125 v.2
74AHC_AHCT125 v.2	19990927	Product specification	-	74AHC_AHCT125 v.1
74AHC_AHCT125 v.1	19990111	Product specification	-	-

## 14. Legal information

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Document status [1][2]	Product status [3]	Definition
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Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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